



Model ID

# MD-P200US2

Model No. NIM-EFF1D

- Contribute to low cost production for high value added devices (High yield and high productivity)  
Productivity improved by 11% (compared with MD-P200US)
- Realize high quality metal joint, thanks to stable ultrasonic vibration provided by high rigidity US head with heating function
- Ensure stable quality and traceability thanks to real time monitoring function

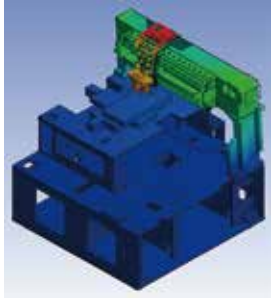
Model ID	MD-P200US2
Model No.	NIM-EFF1D
Productivity *1	0.65 s / IC for thermosonic bonding (Including process time of 0.2 seconds. Under the fastest conditions)
Placement accuracy *1	XY (3σ at PFSC conditions) : ±7 μm
Substrate dimensions	L 50 mm × W 30 mm to L 120 mm × W 120 mm
Die dimensions	L 0.25 mm × W 0.25 mm to L 6 mm × W 6mm
Number of die types	1 product type (manual wafer supply) / Up to 12 product types (AWC specifications) *Nozzle is one type
Die supply	Wafer frame (Max. 8 inch), Tray
Bonding load	VCM head for thermosonic process : 1 N to 50 N (Option : 2 N to 100 N)
Head heating	Up to 300°C for the VCM head
Substrate heating	Constant heating, Up to 300°C
Power source *2	3-phase AC 200 V ±10V, 50 / 60 Hz, Up to 1.7 kVA (Up to 7.5 kVA for heating specification)
Pneumatic source	0.4 to 0.5 Mpa (Max. 0.8 Mpa), 30 L / min (A.N.R.) (Up to 150 L / min for full-featured machine including cooling air)
Dimensions	W 1 340 mm × D 1 140 mm × H 1 400 mm (Including loader/unloader)
Mass	1 750 kg (Including loader / unloader)

\*1: The described productivity and placement accuracy may differ depending on the conditions of use.

\*2: Three phase 208 / 220 / 380 / 400 / 415 / 480  
For details, refer to the specification.

**Productivity improved by 11% (compared with MD-P200US)**

High rigidity design and improved IC quick pick up motion brings improved productivity by 11% (0.65 s / IC), while keeping high accuracy of  $\pm 7 \mu\text{m} / 3\sigma$ , and high productivity.



- [High rigidity design]**
- High rigidity frame
  - light weight bonding head

**Real time US monitoring function**

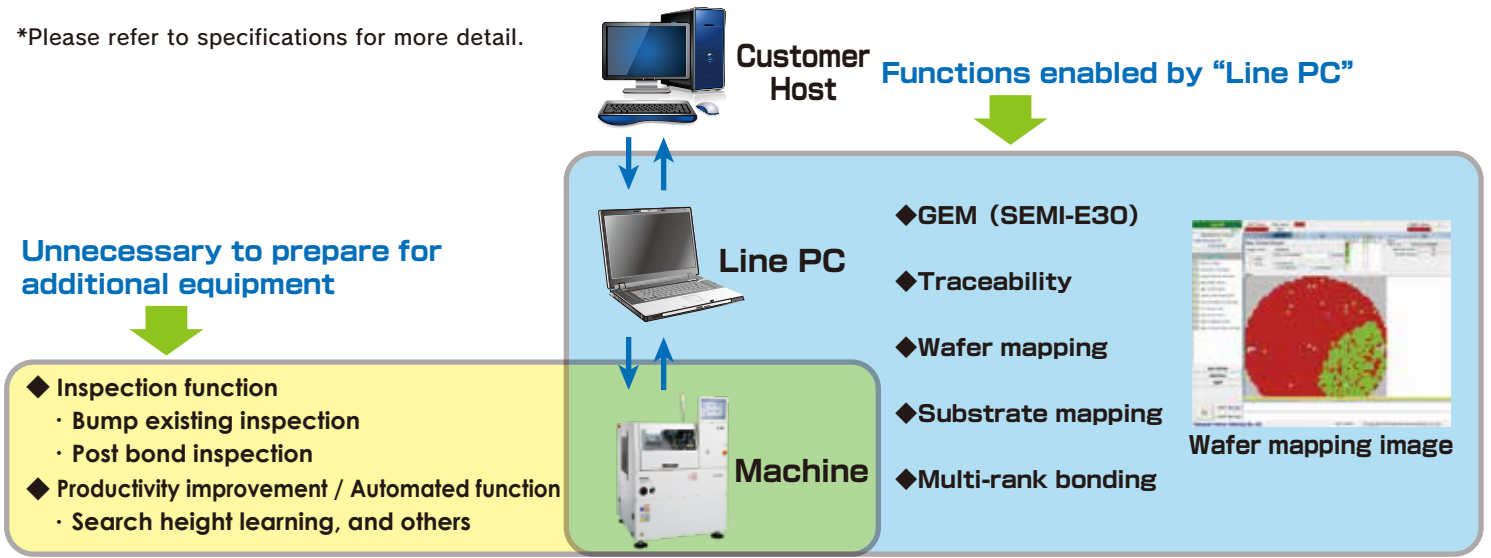
Real time US monitoring function realizes stable quality by monitoring process parameters during production.



**Variation of advanced software functions**

Various advanced software functions (option) will fulfill various requirement, depending on purposes

\*Please refer to specifications for more detail.



**⚠ Safety Cautions**

- Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.
- To ensure safety when using this equipment, all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

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Inquiries...

Panasonic Corporation  
Process Automation Business Division

3-1-1 Inazu-cho, Toyonaka City, Osaka 561-0854, Japan  
TEL +81-6-6866-8630  
FAX +81-6-6862-0422

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